

**• General Description**

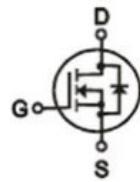
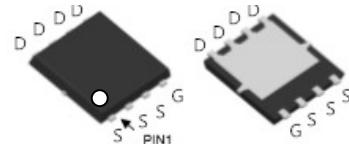
It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- Synchronous Rectification for AC-DC/DC-DC converter
- Oring switches
- Power Tools

• Product Summary $V_{DS} = 100V$ $R_{DS(ON)} = 4.0m\Omega$ $I_D = 160A$ 

DFN5 x 6

• Ordering Information:

Part NO.	ZMS040N10N
Marking	ZMS040N10
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

• Absolute Maximum Ratings ($T_C = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D@T_C=25^\circ C$	160	A
	$I_D@T_C=75^\circ C$	121	A
	$I_D @ T_C=100^\circ C$	100	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	480	A
Total Power Dissipation	$P_D@T_C=25^\circ C$	85	W
Total Power Dissipation	$P_D@T_A=25^\circ C$	3.4	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Storage Temperature	T_{STG}	-55 to 150	$^\circ C$
Single Pulse Avalanche Energy@L=0.1mH	E_{AS}	200	mJ


•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	-	1.5	° C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	37	° C/W
Soldering temperature, wave soldering for 10s	T _{sold}	-	-	265	° C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	100			V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250uA	1.2		2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V			1.0	uA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±20V ,V _{DS} =0V			±100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =25A @ TC=25°C		4.0	5.2	mΩ
		V _{GS} =10V, I _D =25A @ TC=125°C		6.2		mΩ
		V _{GS} =4.5V, I _D =15A @ TC=25°C		5.0	6.5	mΩ
		V _{GS} =4.5V, I _D =15A @ TC=125°C		7.7		mΩ
Forward Transconductance	g _{FS}	V _{DS} =25V, I _D =10A		28		s
Source-drain voltage	V _{SD}	I _S =25A			1.28	V

•Dynamic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz, V _{DS} =25V	-	4028	-	pF
Output capacitance	C _{oss}		-	1960	-	
Reverse transfer capacitance	C _{rss}		-	44	-	
Gate Resistance	R _g	f = 1MHz		3		Ω
Total gate charge	Q _g	V _{DD} = 15V I _D = 5A V _{GS} = 10V	-	48	-	nC
Gate - Source charge	Q _{gs}		-	16	-	
Gate - Drain charge	Q _{gd}		-	4.9	-	
Turn-ON Delay time	t _{D(on)}	V _{GS} =10V, V _{DS} =15V		17		ns
Turn-ON Rise time	t _r			8.5		ns



Turn-Off Delay time	$t_{D(off)}$	$R_G = 6\Omega, I_D = 15A$		45		ns
Turn-Off Fall time	t_f			9		ns
Reverse Recovery Time	t_{RR}	$V_{DD} = 20 V,$ $dI_S/dt = 100A/\mu s,$ $I_S = 30 A$		33		ns
Reverse Recovery Charge	Q_{RR}			170		nC

Note: ① Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;

Fig.1 Gate-Charge Characteristics

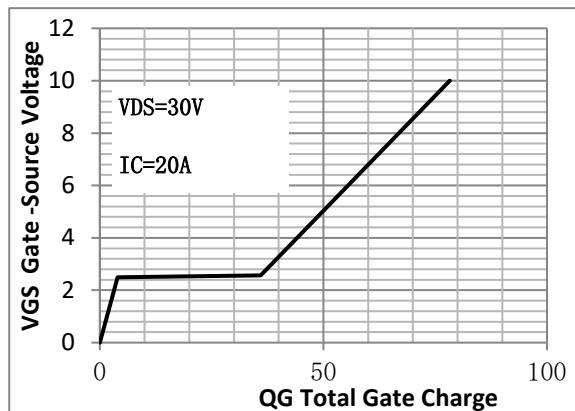


Fig.2 Capacitance Characteristics

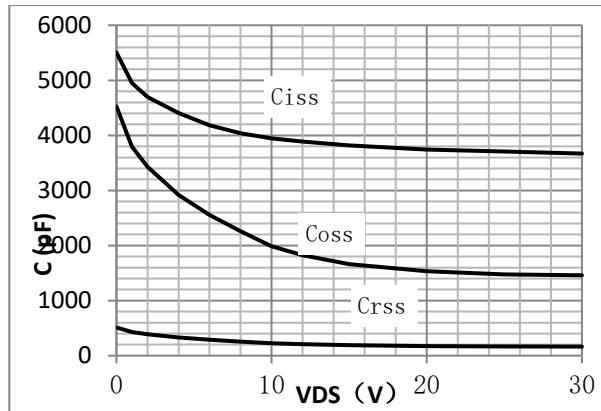


Fig.3 Power Dissipation

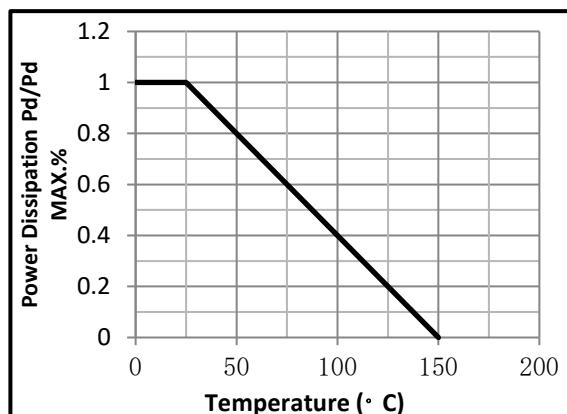


Fig.4 Typical output Characteristics

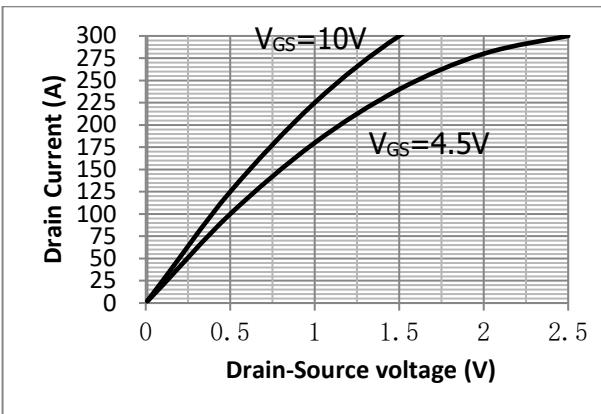


Fig.5 Threshold Voltage V.S Junction Temperature

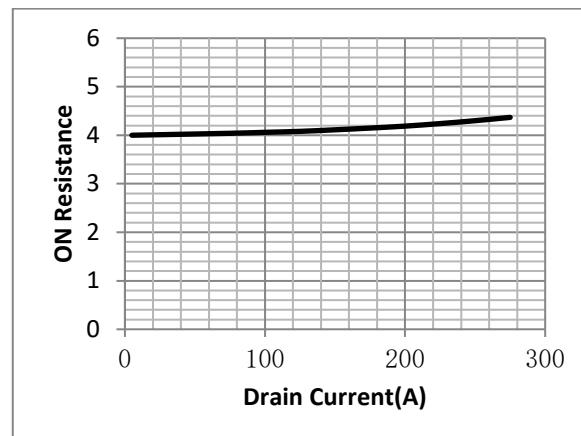
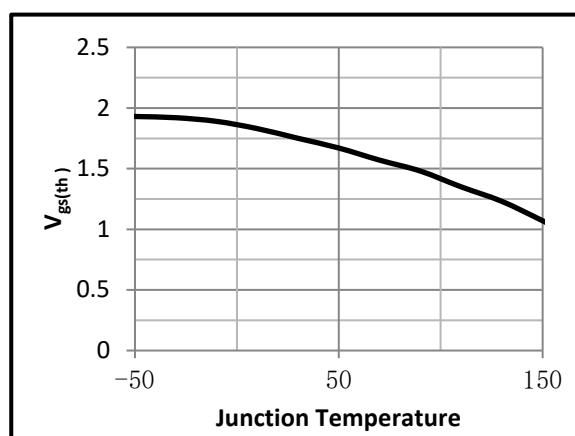




Fig.7 On-Resistance VS Gate Source Voltage

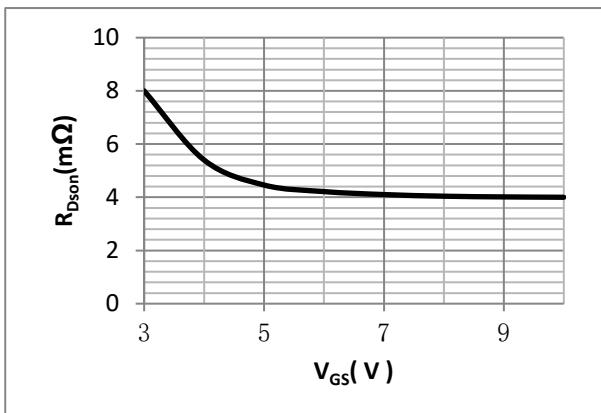


Fig.8 On-Resistance V.S Junction Temperature

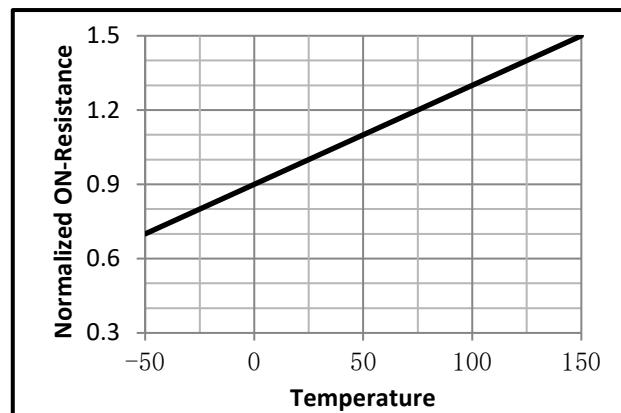


Fig.9 SOA Maximum Safe Operating Area

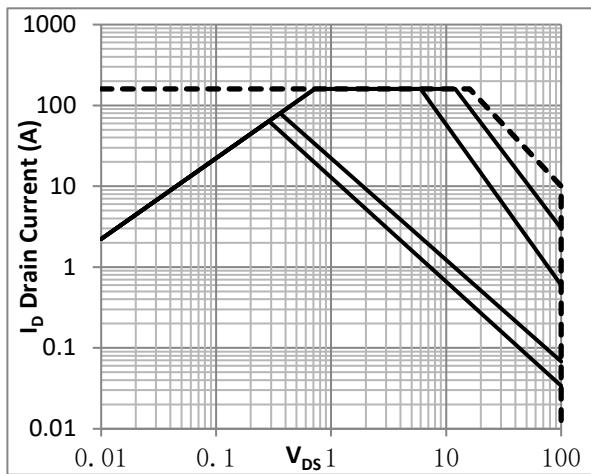


Fig.10 ID-Junction Temperature

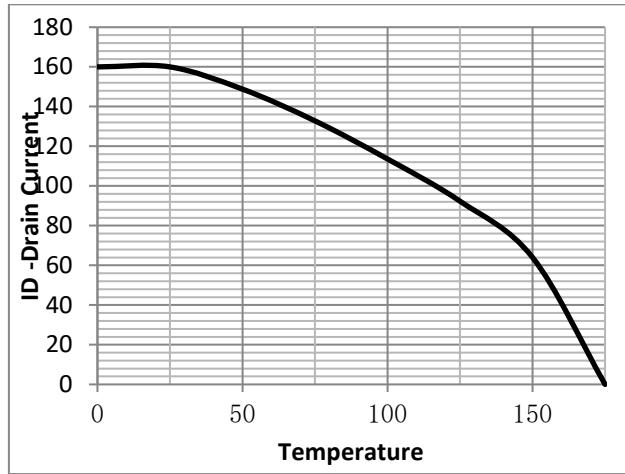


Fig.11 Switching Time Measurement Circuit

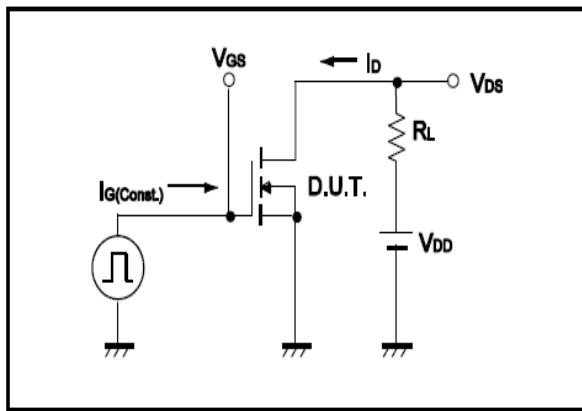


Fig.12 Gate Charge Waveform

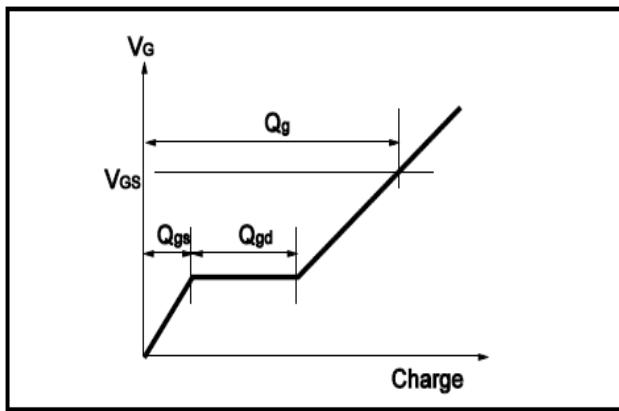




Fig.13 Switching Time Measurement Circuit

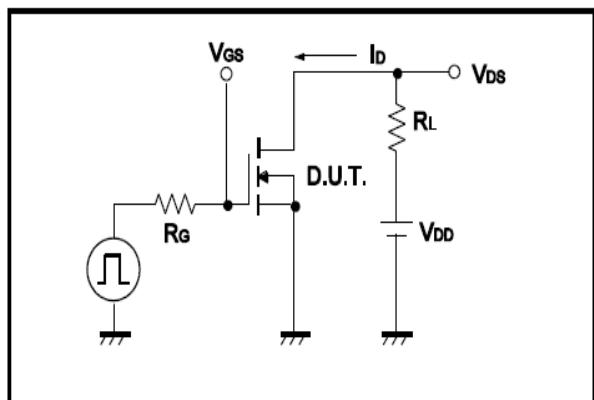


Fig.14 Gate Charge Waveform

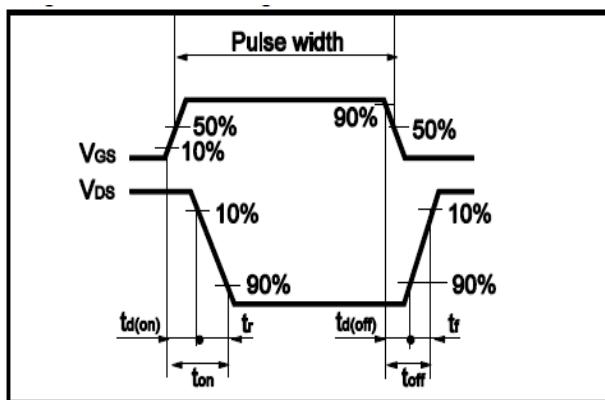


Fig.15 Avalanche Measurement Circuit

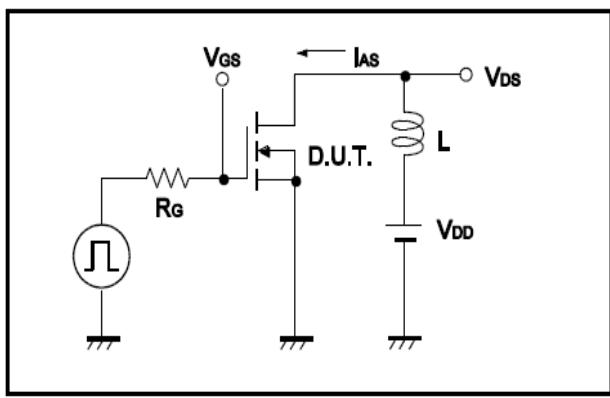
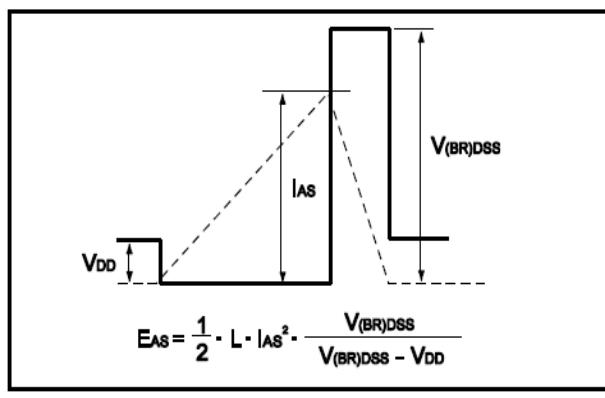


Fig.16 Avalanche Waveform





•Dimensions (DFN5×6)

Unit: mm

